

PRELIMINARY AMENDMENT
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Example 1. With respect to those composition and molded article, various characteristics thereof were measured in the same manner as in Example 1. The results are shown in Table 2.

IN THE CLAIMS:

Please enter the following amended claims:

3. (Amended) The crosslinkable elastomer composition of Claim 1, wherein an average particle size of the ultra fine powders of silicon oxide is from 0.01 to 0.05 μm .

4. (Amended) The crosslinkable elastomer composition of Claim 1, wherein the ultra fine powders of silicon oxide are an amorphous silica.

5. (Amended) The crosslinkable elastomer composition of Claim 1, wherein the ultra fine powders of silicon oxide are surface-treated with hydrofluoric acid.

6. (Amended) The crosslinkable elastomer composition of Claim 1, wherein the ultra fine powders of silicon oxide are surface-treated with a silane coupling agent.

7. (Amended) The crosslinkable elastomer composition of Claim 1, wherein the ultra fine powders of silicon oxide are heat-treated at high temperature of not less than 400°C in an inert gas stream.

8. (Amended) The crosslinkable elastomer composition of Claim 1 which comprises 1 to 150 parts by weight of said ultra fine powders of silicon oxide on the basis of 100 parts by weight of the crosslinkable elastomer component.

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9. (Amended) The crosslinkable elastomer composition of Claim 1 which comprises 0.05 to 10 parts by weight of an organic peroxide, 0.1 to 10 parts by weight of a crosslinking aid and 1 to 150 parts by weight of said ultra fine powders of silicon oxide on the basis of 100 parts by weight of the crosslinkable elastomer component.

10. (Amended) The crosslinkable elastomer composition of Claim 1, wherein the crosslinkable elastomer component is a fluorine-containing elastomer.

12. (Amended) A molded article obtained by crosslinking and molding the crosslinkable elastomer composition of Claim 1.

14. (Amended) The molded article of Claim 12 which is used for semiconductor production apparatuses.

15. (Amended) The molded article of Claim 12 which is a sealing material to be used for sealing of semiconductor production apparatuses.

Please add the following new claims 16-28:

16. (New) The crosslinkable elastomer composition of Claim 2, wherein an average particle size of the ultra fine powders of silicon oxide is from 0.01 to 0.05 μm .

17. (New) The crosslinkable elastomer composition of Claim 2, wherein the ultra fine powders of silicon oxide are an amorphous silica.

18. (New) The crosslinkable elastomer composition of Claim 2, wherein the ultra fine powders of silicon oxide are surface-treated with hydrofluoric acid.

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19. (New) The crosslinkable elastomer composition of Claim 2, wherein the ultra fine powders of silicon oxide are surface-treated with a silane coupling agent.

20. (New) The crosslinkable elastomer composition of Claim 2, wherein the ultra fine powders of silicon oxide are heat-treated at high temperature of not less than 400°C in an inert gas stream.

21. (New) The crosslinkable elastomer composition of Claim 2 which comprises 1 to 150 parts by weight of said ultra fine powders of silicon oxide on the basis of 100 parts by weight of the crosslinkable elastomer component.

22. (New) The crosslinkable elastomer composition of Claim 2 which comprises 0.05 to 10 parts by weight of an organic peroxide, 0.1 to 10 parts by weight of a crosslinking aid and 1 to 150 parts by weight of said ultra fine powders of silicon oxide on the basis of 100 parts by weight of the crosslinkable elastomer component.

23. (New) The crosslinkable elastomer composition of Claim 2, wherein the crosslinkable elastomer component is a fluorine-containing elastomer.

24. (New) The crosslinkable elastomer composition of Claim 23, wherein the fluorine-containing elastomer is a perfluoro elastomer.

25. (New) A molded article obtained by crosslinking and molding the crosslinkable elastomer composition of Claim 2.

26. (New) The molded article of Claim 25, wherein an amount of dioctylphthalate gas to be generated when heating at 200°C for 15 minutes is not more than 3 ppb.

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Cont 27. (New) the molded article of claim 25 which is used for semiconductor production
AS apparatuses.

28. (New) The molded article of Claim 25 which is a sealing material to be used for
sealing of semiconductor production apparatuses.

